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THIN FILM DEPOSITION



Vacuum Systems Technologies and Services Ltd.

TFDS - 462

THIN FILM DEPOSITION SYSTEM



The TFDS 462 line is design for R&D laboratories to offer best value to cost ratio. The exceptional flexibility and the wide range of components available, allows the perfect fit of the system to the researcher needs. Most of the known deposition sources such as thermal evaporation, electron beam, ion beam, sputtering, etc. can be integrated. The small chamber volume allows fast cycling to enable several runs per day with dry and wet pumping system according to process requirements. For even faster and cleaner cycling the system comes with load lock, to avoid opening the chamber to air. The process chamber can be either bell jar type or box type each with its advantages. All chambers are coming with protective liners, easy removable for cleaning purpose. The system is fully automated and it comes either with PC control or in the low cost version, PLC control. The human friendly engineering offers safe operation fully protected against operator errors. Several levels of security are used to differentiate operators, engineers, or service users. When PC is integrated, all processes runs as well as recipes are saved and can be review, modified and reused. The automatic recording feature, works as data logger for all analog available data. The recorded data can be review online and offline as required.



Different types of process chambers:

- Bell jar
- Box chamber
- Clean room wall mount
- Load-lock system



Variety of substrate holders:

- Cooling and cryogenic cooling
- Heating
- Rotating
- Tilting
- Positioning
- Biasable



Several pumping system:

- Oil roughing pump
- Dry scroll pump
- Turbomolecular pump
- Cryogenic pump



Options:

- Gas supply, manual or automatical system
- Pumping throtteling system
- Glow discharge, etc.

Variety of deposition sources, including thermal deposition, RF or DC sputtering, E-beam, ion gun, etc.

